



N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY								
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A) ^a	Q _g (Typ.)					
100	0.083 at $V_{GS} = 10 \text{ V}$	11.3	3.5 nC					
	$0.130 \text{ at V}_{GS} = 4.5 \text{ V}$	9	3.5 110					

PowerPAK SC-70-6L-Single 2.05 mm **Bottom View**

Ordering Information: SiA416DJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

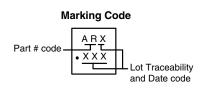
- TrenchFET® Power MOSFET
- 100 % R_q and UIS Tested
- Material categorization: For definitions of compliance please www.vishay.com/doc?99912

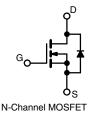


COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- Full-Bridge Converters
- For Power Bricks and POL Power





Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V		
Gate-Source Voltage		V _{GS}	± 20			
	T _C = 25 °C		11.3			
Continuous Drain Current (T. 150 °C)	T _C = 70 °C		9			
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	4.8 ^{b, c}			
	T _A = 70 °C		3.9 ^{b, c}			
Pulsed Drain Current (t = 300 μs)	'	I _{DM}	15	Α		
Continuous Courses Dunin Biode Coursest	T _C = 25 °C	1	12			
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.9 ^{b, c}			
Single Pulse Avalanche Current		I _{AS}	3	\neg		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	0.45	mJ		
	T _C = 25 °C		19			
Mariana Barra Birahakan	T _C = 70 °C		12			
Maximum Power Dissipation	T _A = 25 °C	P _D	3.5 ^{b, c}	W		
	T _A = 70 °C		2.2 ^{b, c}			
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150				
Soldering Recommendations (Peak Temperature	e) ^{d, e}	,	260	- °C		

THERMAL RESISTANCE RATINGS									
Parameter		Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R_{thJA}	28	36	°C/W				
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	5.3	6.5	O/ VV				

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 80 °C/W.



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted									
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit			
Static									
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V			
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		54		mV/°C			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η η = 250 μΑ		- 4.4					
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.6		3	V			
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA			
Zava Cata Valtaga Dvain Curvent	1	V _{DS} = 100 V, V _{GS} = 0 V			1				
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α			
	Б	$V_{GS} = 10 \text{ V}, I_D = 3.2 \text{ A}$	0.068	0.083					
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 2.6 \text{ A}$		0.092	0.130	Ω			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 3.2 \text{ A}$		8		S			
Dynamic ^b					I .				
Input Capacitance	C _{iss}			295		pF			
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		92					
Reverse Transfer Capacitance	C _{rss}			16					
		$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4.8 \text{ A}$		6.5	10	nC			
Total Gate Charge	Qg			3.5	5.3				
Gate-Source Charge	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4.8 \text{ A}$		1.2					
Gate-Drain Charge	Q_{gd}			1.9					
Output Charge	Q _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$		7.6		1			
Gate Resistance	R_{g}	f = 1 MHz	0.4	1.8	3.6	Ω			
Turn-On Delay Time	t _{d(on)}			5	10				
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 12.8 \Omega$		13	25				
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 3.9 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	20				
Fall Time	t _f			10	20	1			
Turn-On Delay Time	t _{d(on)}			25	50	ns			
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 12.8 \Omega$		100	200				
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 3.9 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		15	30				
Fall Time	t _f			25	50				
Drain-Source Body Diode Characteristic	s				•	•			
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			12	Α			
Pulse Diode Forward Current ^a	Diode Forward Current ^a I _{SM}				15				
Body Diode Voltage	V_{SD}	I _S = 3.9 A		0.85	1.2	V			
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns			
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 3.9 A, dl/dt = 100 A/μs, T _{.I} = 25 °C		30	60	nC			
Reverse Recovery Fall Time	t _a	$I_{\rm F} = 3.9 \text{ A}, \text{ al/at} = 100 \text{ A/}\mu\text{s}, I_{\rm J} = 25 ^{\circ}\text{C}$		20		ns			
Reverse Recovery Rise Time	t _b			10					

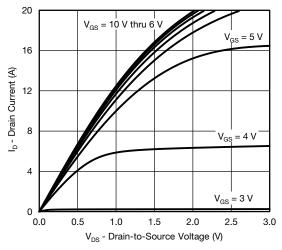
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

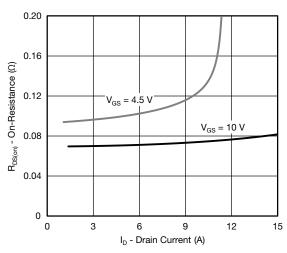
b. Guaranteed by design, not subject to production testing.



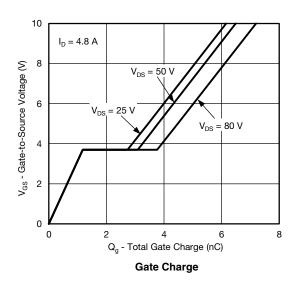
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

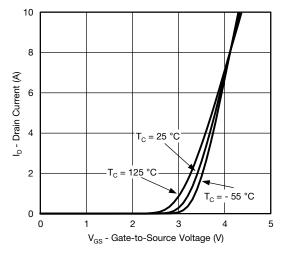


Output Characteristics

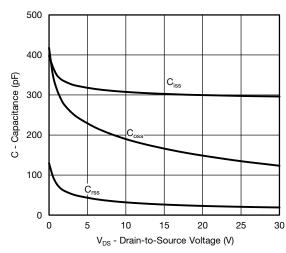


On-Resistance vs. Drain Current and Gate Voltage

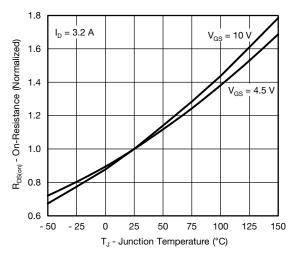




Transfer Characteristics

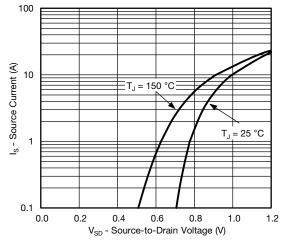


Capacitance

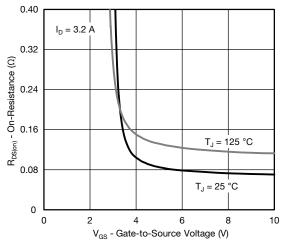


On-Resistance vs. Junction Temperature

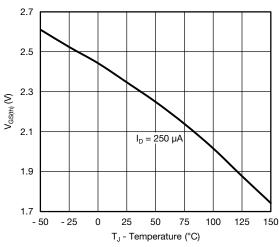
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



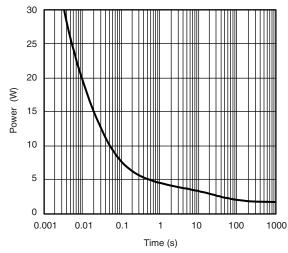
Source-Drain Diode Forward Voltage



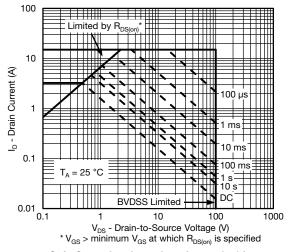
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



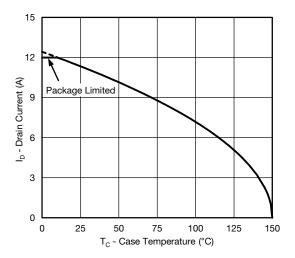
Single Pulse Power, Junction-to-Ambient



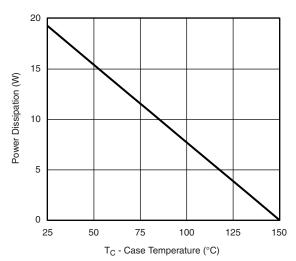
Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*

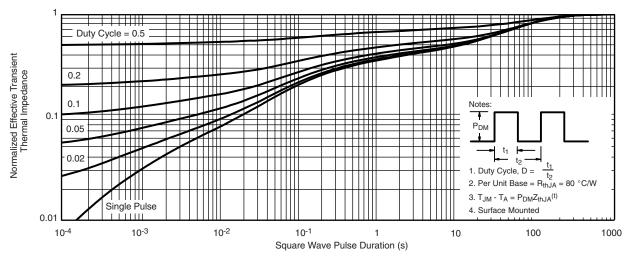


Power, Junction-to-Case

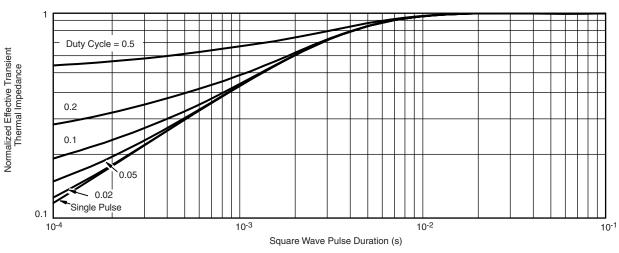
 $^{^{\}star}$ The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



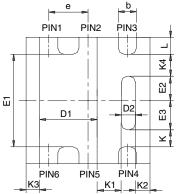
Normalized Thermal Transient Impedance, Junction-to-Case

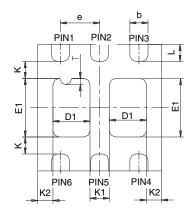
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?63649.





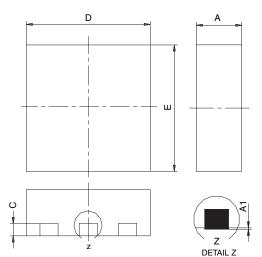
PowerPAK® SC70-6L





BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL



- All dimensions are in millimeters
 Package outline exclusive of mold flash and metal burr
 Package outline inclusive of plating

		SINGLE PAD						DUAL PAD				
DIM	M	ILLIMETER	RS		INCHES		М	ILLIMETER	RS		INCHES	
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
Α	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A 1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
С	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
е		0.65 BSC			0.026 BSC	;	0.65 BSC			0.026 BSC		
K		0.275 TYP			0.011 TYP	1	0.275 TYP		0.011 TYP			
K1		0.400 TYP			0.016 TYP		0.320 TYP		0.013 TYP			
K2		0.240 TYP		0.009 TYP		0.252 TYP		0.010 TYP				
К3		0.225 TYP		0.009 TYP								
K4		0.355 TYP		0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
Т							0.05	0.10	0.15	0.002	0.004	0.006
ECN: C O	07421 Pay C 06 Aug 07											

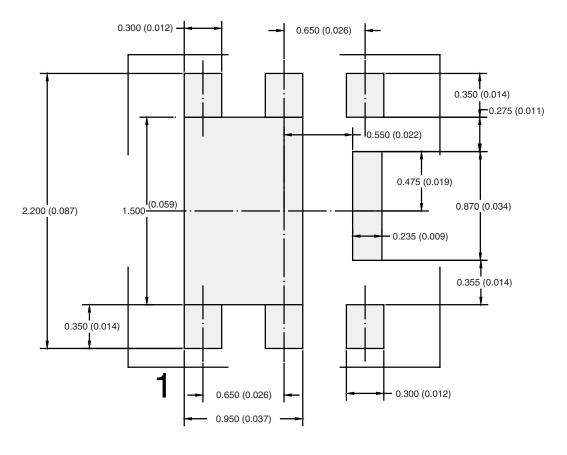
ECN: C-07431 - Rev. C, 06-Aug-07

DWG: 5934

Document Number: 73001 06-Aug-07



RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single



Dimensions in mm/(Inches)

Return to Index

ATTLICA ION NOI



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.